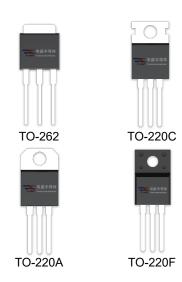
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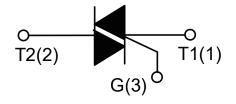
#### **DESCRIPTION:**

With high ability to withstand the shock loading of large current, BTA12-600CW series triacs provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended for use on inductive load.



#### **MAIN FEATURES**

Symbol	Value	
I <sub>T(RMS)</sub>	I <sub>T(RMS)</sub> 12	
V <sub>DRM</sub> /V <sub>RRM</sub>	600/800/1200	V



### **ABSOLUTE MAXIMUM RATINGS**

Parameter		Symbol	Value	Unit		
Storage junction temperature range		T <sub>stg</sub>	-40-150	$^{\circ}\!\mathbb{C}$		
Operating junction	perating junction temperature range		rating junction temperature range		-40-125	$^{\circ}\!\mathbb{C}$
Repetitive peak off	-state voltage (T <sub>j</sub> =25℃)	V <sub>DRM</sub>	600/800/1200	V		
Repetitive peak rev	verse voltage (T <sub>j</sub> =25℃)	V <sub>RRM</sub>	600/800/1200	V		
Non repetitive surge peak Off-state voltage		V <sub>DSM</sub>	V <sub>DRM</sub> +100	V		
Non repetitive peak reverse voltage		VRSM	V <sub>RRM</sub> +100	V		
	TO-220A(Ins) (Tc=85°C)					
RMS on-state current	TO-262/ TO-220A(Non-Ins)/ TO-220C(Tc=100°C) TO-220F(Ins) (Tc=80°C)	I <sub>T(RMS)</sub>	12	А		



Non repetitive surge peak on-state current (full cycle, F=50Hz)		I <sub>TSM</sub>	120	А
I <sup>2</sup> t value for fusing (tp=10ms)		l²t	78	A <sup>2</sup> s
Critical rate of rise of on-state current ( $I_G = 2 \times I_{GT}$ )		dl/dt	50	A/µs
Peak gate current		Ідм	4	Α
Average gate power dissipation		P <sub>G(AV)</sub>	1	W
Peak gate power		P <sub>GM</sub>	5	W

# **ELECTRICAL CHARACTERISTICS** ( $T_j$ =25 $^{\circ}$ C unless otherwise specified)

# 3 Quadrants

Symbol Test Condition	Toot Condition Overdrent	\			Value			
	Quadrant	BW	CW	sw	TW	Unit		
Ідт	\/ <sub>0</sub> =12\/ B₁ =22O	I - II -III	MAX	50	35	10	5	mA
V <sub>GT</sub>	$V_D = 12V R_L = 33\Omega$	I - II -III	MAX		1.3	3		V
V <sub>GD</sub>	$V_D = V_{DRM} T_j = 125^{\circ}C$ $R_L = 3.3 K\Omega$	I - II -III	MIN	0.2		V		
I.	I <sub>L</sub> I <sub>G</sub> = 1.2I <sub>GT</sub>	I -III	MAX	80	50	30	20	mΛ
IL IL		II	IVIAA	90	60	40	30	mA
Ін	I <sub>T</sub> =100mA		MAX	60	40	20	15	mA
dV/dt	V <sub>D</sub> =2/3V <sub>DRM</sub> Gate Open T <sub>j</sub> =125℃		MIN	1000	500	200	100	V/µs
(dl/dt)c	Without snubber T <sub>j</sub> =125℃		MIN	12	6.5	-	-	A/ms

### 4 Quadrants

Symbol	Test Condition Overdrant		Test Condition	Quadrant		Va	lue	Unit
	rest Condition	Quaurant		В	С	Oilit		
lo-		I - II -III	MAX	50	25	mΛ		
I <sub>GT</sub>	V <sub>D</sub> =12V R <sub>L</sub> =33Ω	IV	IVIAA	70	50	mA		
V <sub>G</sub> T		ALL	MAX	1	.3	V		
V <sub>GD</sub>	$V_D = V_{DRM} T_j = 125^{\circ}C$ $R_L = 3.3 K\Omega$	ALL	MIN	0.2		V		
IL	1 -4 01	I -III-IV	MAX	50	40	mΛ		
	I <sub>G</sub> =1.2I <sub>GT</sub>	II	IVIAA	100	80	- mA		



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Ін	I <sub>T</sub> =100mA	MAX	50	25	mA
dV/dt	V <sub>D</sub> =2/3V <sub>DRM</sub> Gate Open T <sub>j</sub> =125℃	MIN	500	200	V/µs
(dV/dt)c	(dl/dt)c=5.3A/ms T <sub>j</sub> =125℃	MIN	10	5	V/µs

### **STATIC CHARACTERISTICS**

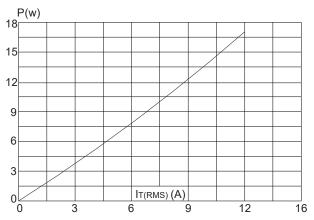
Symbol	Parameter		Value(MAX)	Unit
V <sub>TM</sub>	I <sub>TM</sub> =17A tp=380µs	Tj=25℃	1.5	V
IDRM	\/\/\/	T <sub>j</sub> =25℃	5	μΑ
I <sub>RRM</sub>	$V_D = V_{DRM} V_R = V_{RRM}$	T <sub>j</sub> =125℃	1	mA

# **THERMAL RESISTANCES**

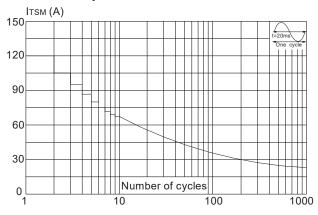
Symbol	Parameter		Value	Unit
		TO-220A(Ins)	2.3	
R <sub>th(j-c)</sub>	junction to case(AC)	TO-262/ TO-220A(Non-Ins)/ TO-220C	1.4	°C/W
		TO-220F(Ins)	2.5	



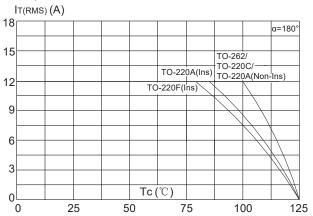
**FIG.1** Maximum power dissipation versus RMS on-state current



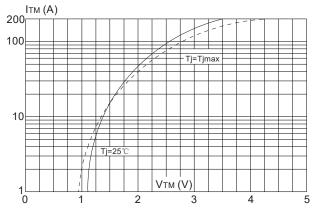
**FIG.3:** Surge peak on-state current versus number of cycles



**FIG.2:** RMS on-state current versus case temperature

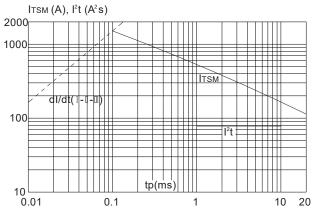


**FIG.4:** On-state characteristics (maximum values)



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**FIG.5:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<20ms, and corresponging value of  $I^2t$  (dI/dt( I-I-II) < 50A/ $\mu$ s)



**FIG.6:** Relative variations of gate trigger current, holding current and latching current versus junction temperature

